Shenzhen Dinghua Technology Development Co., LTD.

Product Introduction

Company Profile

Dinghua

Shenzhen Dinghua Technology Development Co., LTD.

- Years experiences in SMT/BGA rework industry.
- Research, Develop, Design, Manufacture and Export BGA Rework Station, Automatic Soldering Machine, Automatic Glue Dispenser, Automatic Screw Locking Machine.
- 38 Patents And 97 Quality Control Process
- China National High-Tech Enterprise, IPC certified, SMT Association Membership, etc.
- One of leading manufacturers in China as a professional Rework Solution Provider.

Business Partners

SAMSUNG

HUAWEI

Google

LG

FOXCONN
富士康科技集团

lenovo联想

TCL

Product Presentation

Dinghua

SAMSUNG

FOXCONN
富士康科技集團

BGA Rework Station

Model:DH-A2E

- **Full Automatic & Manual Optional**
- **CCD Optical Alignment System Placeing Prision:0.015mm**
- **Repair Success Rate: 99%+**
- **Touch screen control**
- **Laser Positioning**
- **Auto feeding system**

Power	5300W
Top heater	Hot air 1200W
Bottom heater	Hot air 1200W, Infrared 2700W
Power supply	AC220V±10% 50/60Hz
Dimension	L530*W670*H790 mm
Positioning	V-groove PCB support, and with external universal fixture
Temperature control	K type thermocouple, closed loop control, independent heating
Temperature accuracy	±2°C
PCB size	Max 450*490 mm, Min 22*22 mm
Workbench fine-tuning	±15mm forward/backward,±15mm right/left
BGA chip	80*80-1*1mm
Minimum chip spacing	0.15mm
Temp Sensor	1(optional)
Net weight	70kg

Product Image

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Function

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Operation System

- Manual or full automatic modes available. Built-in PLC precise control.
- Automatically solder, desolder, mount, pick and replace chip. Auto feeding system.
- User-friendly

1.Automatically pick up and place chips.

2.Built-in pressure testing device, can detect pressure of 0.5g. While the test ing device detect pressure, the head of machine will stop declining automatically to protect the PCB from being damaged.

3.Different sizes of vacuum sucker work for different sizes of chip.

Auto feeding system enabled.

1.Desoldering: mounting head auto pick up bga chip and place it on the feeding plate.

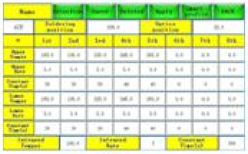
2.Soldering: mounting head auto pick up bga chip from feeding plate.

7'' HD Touch screen

Resolution: 800*480

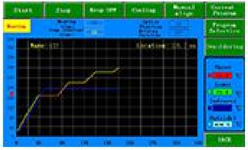
You can choose Desolder/Solder/Mount function.

4.English,Spanish,French and other languages systems available.



1.Can set different temperatures according to different types of BGA

2.Multi storage for temperature profiles for different PCB. Same PCB uses same profile.Time- Saving.



Instantly analyze temperature on touch screen, which effectively avoids failed repairing.

Joystick control

1.CCD lens zoom in/out

2.Up/down movement of top head

Function

Strict Temperature Control System

Even and focused heating efffectively avoid fake or bad soldering and increase success rate of repairing.

●8 segments rising temperature/constant time/temperature rising slope , It can save tens of thousands of groups temperature curves.

●It uses k-type thermocouple closed-loop control and PID automatic temperature compensation system, together with PLC and temperature module to enable precise temperature deviation to ±2 degree centigrade.

●The external sensor can detect temperature precisely, analyze and calibrate the real temperature curve accurately at any time.

Top Heater (Hot Air 1200W)

1.Reflow vent design ensure focused and even heating, effectively increase success rate of repairing chips.

2.Top hot air flow is adjustable, to meet the demand of any chips.

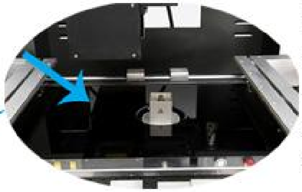
●Top heater can be equipped with different size of nozzles for different size of chip.

●Reflow vent design makes heating even, effectively increase success rate of repairing

Top Air Flow Adjust Button

1.With top air speed adjustable function, prevent small BGA chip from moving flow by strong air.

2.Make air flow suitable for chips of different sizes.



High temperature resistance ceramic glass

1.Prevent IC chip from being dropped and burnt.

2.Infrared heating is more easily absorbed by PCB.

3.More effectively prevent PCB from deformation Make heanting more evenly.

Bottom Heater (Hot Air 1200W)

Nozzles of different size availble for different chips.

Height of bottom heater is adjustable

Distance between PCB and bottom nozzles can be adjusted with this rotary handle. Suitable distance is 1-3 mm.

Function

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Precision Optical Alignment System

- Effectively monitor alignment of every soldering joint and increase success rate of repairing.
- Color optical system with functions of split vision, two color separation, zoom in/out and micro-adjust, equipped with aberration detection device, with auto focus and software operation

HD digital dispaly

Effectively show conditions of alignment of soldering joint.

On the image, red point is for soldering point on PCB while blue point is for IC chip.

Precise CCD optical alignment system.

1.6 million pixels.

2.Mounting accuracy within 0.01mm.

3.Brand: Panasonic

Micrometer

1.Slightly adjust angle of IC chip for precise alignment.

2.Mounting accuracy within 0.01mm.

3.Effectively increase success rate of repairing.

1.Slightly adjust brightness of LED light of CCD lens in up/down direction.

2.Ensure precision alignment.

3.Increase success rate.

Mrcrometer

Slightly adjust position of PCB to ensure Precision alignment of every soldering joint, effectively increase success rate of repairing

Function

Safety system

- With automatic power-off protection device when abnormal accident happens, with a double over-heating protection control.
- CE certified

Built-in pressure testing device, can detect pressure of 0.5g. While the test ing device detect pressure, the head of machine will stop declining automatically to protect the PCB from being damaged.

Cool air flow will be from top and bottom nozzles as soon as soldering/desoldering process finish, High temperature will drop to normal temperature soon.

Voice warning
5 seconds before soldering/desoldering process complete.

Electric leackage Switch
Ensure 100% percent safety of operator and machine.

Powerful Cross-flow cooling fan
1.Cooling fan produces cross cool air flow as soon as soldering/desoldering process finish, which effectively avoid deformation of PCB.

1.Press emergency stop in case of any emergency.
2.Automatic power-off switch in case of emergency.

Function

Other Functions

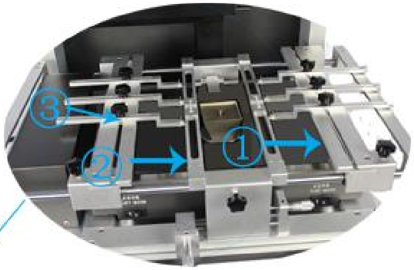
Built-in infrared laser positioning, help fast positioning for PCB board.

LED headlamp

1.Super bright

2.Imported from Taiwan.

3.It can help you clearly see the melting condition of solder ball and check if there is any dirt on PCB and chip.



Flexible ways available for PCB position

1.①Position:V-groove+②PCB support+③universal fixtures. Different ways for different PCB.

Bliwing Cylinder

2.Movable PCB shelf.

3.Composed of 16mm chrome plated rod. Very stable and strong.

USB port

1.Transfer information(temperature profile) to computer.

2.Update system.

Packing List

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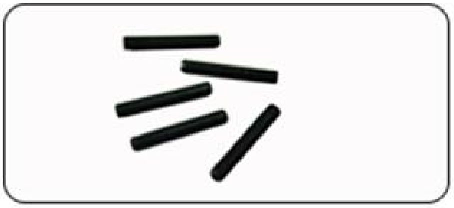

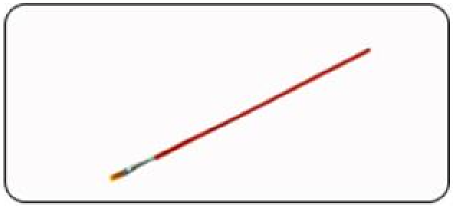

Certificates

Dinghua


Shenzhen Tian Hai Test Technology Co.,Ltd.

CE Certificate of Conformity


Certificate of Registration

MOODY

Shenzhen Dinghua Technology Development Co.,Ltd.
3rd Floor, 4SB Building, Da Yangtian Industrial District, Wanfeng Village, Shajing Town, Bao'an Area, Shenzhen City, China

ISO 9001 : 2008

111004007

Certificate of Registration

MOODY

深圳市鼎华科技发展有限公司

ISO 9001: 2008

111004007


实用新型专利证书


外观设计专利证书


高新技术企业

证书

企业名称：深圳市鼎华科技发展有限公司　　证书编号：GR201344200016

发证时间：二〇一三年九月六日　　有 效 期：三年

批准机关：


中国质量诚信企业协会

全国质量诚信 AAA 级品牌企业

荣誉证书

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